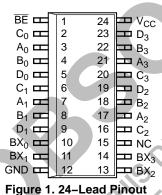
# 4-Bit, 4-Port Bus Exchange Switch

The ON Semiconductor 74FST3400 is a 4–bit, 4–port bus exchange switch. The device is CMOS TTL compatible when operating between 4.0 and 5.5 Volts. The device exhibits extremely low  $R_{\rm ON}$  and adds nearly zero propagation delay. The device adds no noise or ground bounce to the system.

#### **Features**

- $R_{ON} < 4 \Omega$  Typical
- Less Than 0.25 ns-Max Delay Through Switch
- Nearly Zero Standby Current
- No Circuit Bounce
- Control Inputs are TTL/CMOS Compatible
- Pin-For-Pin Compatible With QS3400, FST3400, CBT3400
- All Popular Packages: SOIC-24, TSSOP-24, QSOP-24
- All Devices in Package TSSOP are Inherently Pb-Free\*



#### **TRUTH TABLE**

BE	BX <sub>0</sub>	BX <sub>1</sub>	BX <sub>2</sub>	BX <sub>3</sub>	A0-3	B0-3	Function
Н	Х	Х	Х	Х	Hi–Z	Hi–Z	Disconnect
L		BXi	= L		C0-3	D0-3	Connect
L	BXi = H			D0-3	C0-3	Exchange	

NOTE: H = HIGH Voltage Level, L = LOW Voltage Level, X = Don't Care,  $Hi-Z = High \ Impedance, \ i = 0, 1, 2 \ or 3$ 



# ON Semiconductor®

http://onsemi.com

#### MARKING DIAGRAMS

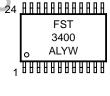


SOIC-24 DW SUFFIX CASE 751E



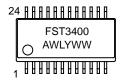


TSSOP-24 DT SUFFIX CASE 948H





QSOP-24 QS SUFFIX CASE 492B



A = Assembly Location

L, WL = Wafer Lot Y, YY = Year W, WW = Work Week

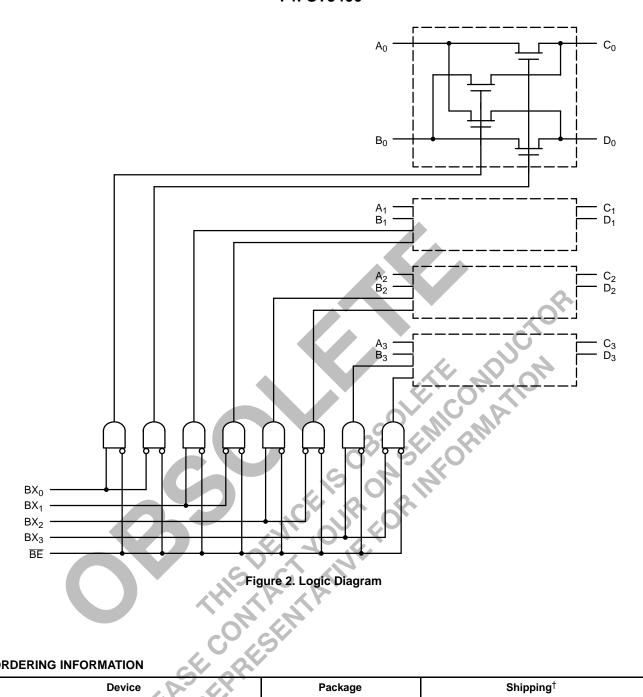
#### **PIN NAMES**

Pin	Description		
BE	Bus Enable Input (Active LOW)		
Ax, Bx, Cx, Dx	Bus A, Bus B, Bus C, Bus D		
BX <sub>0</sub>	Bus Exchange (Bit 0)		
BX <sub>1</sub>	Bus Exchange (Bit 1)		
BX <sub>2</sub>	Bus Exchange (Bit 2)		
BX <sub>3</sub>	Bus Exchange (Bit 3)		
NC	No Connect		
GND	Ground		
V <sub>CC</sub>	Power		

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
74FST3400DW	SOIC-24	30 Units / Rail
74FST3400DWR2	SOIC-24	1000 / Tape & Reel
74FST3400DT	TSSOP-24* (Pb-Free)	62 Units / Rail
74FST3400DTR2	TSSOP-24* (Pb-Free)	2500 / Tape & Reel
74FST3400QS	QSOP-24	55 Units / Rail
74FST3400QSR	QSOP-24	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb–Free.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5  to  +7.0	V
VI	DC Input Voltage	-0.5  to  +7.0	V
Vo	DC Output Voltage	-0.5 to $+7.0$	V
I <sub>IK</sub>	DC Input Diode Current $V_I < GND$	-50	mA
I <sub>OK</sub>	DC Output Diode Current $V_{O} < GND$	-50	mA
IO	DC Output Sink Current	128	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±100	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	+ 150	°C
$\theta_{\sf JA}$	Thermal Resistance SOIC TSSOP QSOP	125 170 200	°C/W
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage  Human Body Model (Note 1)  Machine Model (Note 2)  Charged Device Model (Note 3)	>2000 >200 N/A	V
I <sub>Latchup</sub>	Latchup Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 4)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect ter device reliability.

- 1. Tested to EIA/JESD22-A114-A.
- 2. Tested to EIA/JESD22-A115-A.
- Tested to JESD22-C101-A.
- 4. Tested to EIA/JESD78.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating, Data Retention Only	4.0	5.5	V
VI	Input Voltage (Note 5)	0	5.5	V
Vo	Output Voltage (HIGH or LOW State)	0	5.5	V
T <sub>A</sub>	Operating Free-Air Temperature	-40	+85	°C
Δt/ΔV	$\begin{array}{ccc} \text{Input Transition Rise or Fall Rate} & \text{Switch Control Input} \\ \text{Switch I/O} & \text{V}_{\text{CC}} = 5.0 \text{ V} \pm 0.5 \text{ V} \end{array}$	0	DC 5	ns/V

5. Unused control inputs may not be left open. All control inputs must be tied to a high or low logic input voltage level.

#### DC ELECTRICAL CHARACTERISTICS

				T <sub>A</sub> = -	40°C to	+85°C	
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Тур*	Max	Unit
$V_{IK}$	Clamp Diode Resistance	$I_{IN} = -18mA$	4.5			-1.2	V
$V_{IH}$	High-Level Input Voltage		4.0 to 5.5	2.0			V
V <sub>IL</sub>	Low-Level Input Voltage		4.0 to 5.5			0.8	V
I <sub>I</sub>	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5			±1.0	μΑ
I <sub>OZ</sub>	OFF-STATE Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μΑ
R <sub>ON</sub>	Switch On Resistance (Note 6)	V <sub>IN</sub> = 0 V, I <sub>IN</sub> = 64 mA	4.5		4	7	Ω
		V <sub>IN</sub> = 0 V, I <sub>IN</sub> = 30 mA	4.5		4	7	
		V <sub>IN</sub> = 2.4 V, I <sub>IN</sub> = 15 mA	4.5		8	15	
		V <sub>IN</sub> = 2.4 V, I <sub>IN</sub> = 15 mA	4.0		11	20	
Icc	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND, I <sub>OUT</sub> = 0	5.5			3	μΑ
$\Delta I_{CC}$	Increase In I <sub>CC</sub> per Input	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5			2.5	mA

#### **AC ELECTRICAL CHARACTERISTICS**

		-0			to +85°0 = RD = 5		
		250	V <sub>CC</sub> = 4	.5–5.5 V	V <sub>CC</sub> =	4.0 V	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t <sub>PHL</sub> ,	Prop Delay Bus to Bus (Note 7)	V <sub>I</sub> = OPEN	71	0.25		0.25	ns
t <sub>PLH</sub>	Prop Delay, BXn to An, Bn, Cn or Dn	4, 0	1.0	5.3		6.0	1
t <sub>PZH</sub> ,	Output Enable Time, BXn to An, Bn, Cn or Dn	$V_I = 7 \text{ V for } t_{PZL}$	1.0	5.8		6.5	ns
$t_{PZL}$	Output Enable Time, I <sub>OE</sub> to An, Bn, Cn or Dn	$V_I = OPEN$ for $t_{PZH}$	1.0	5.8		6.5	1
t <sub>PHZ</sub> ,	Output Disable Time, BXn to An, Bn, Cn or Dn	$V_I = 7 \text{ V for } t_{PLZ}$	1.0	5.3		6.2	ns
t <sub>PLZ</sub>	Output Disable Time, I <sub>OE</sub> to An, Bn, Cn or Dn	$V_I = OPEN$ for $t_{PHZ}$	1.0	5.3		6.2	

<sup>7.</sup> This parameter is guaranteed by design but is not tested. The bus switch contributes no propagation delay other than the RC delay of the typical On resistance of the switch and the 50 pF load capacitance, when driven by an ideal voltage source (zero output impedance).

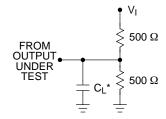
#### **CAPACITANCE** (Note 8)

Symbol	Parameter	Conditions	Тур	Max	Unit
C <sub>IN</sub>	Control Pin Input Capacitance	V <sub>CC</sub> = 5.0 V	6		pF
C <sub>I/O</sub>	Port Input/Output Capacitance	$V_{CC}$ , $\overline{OE} = 5.0 \text{ V}$	13		pF

<sup>8.</sup>  $T_A = +25$ °C, f = 1 MHz, Capacitance is characterized but not tested.

<sup>\*</sup>Typical values are at V<sub>CC</sub> = 5.0 V and T<sub>A</sub> = 25°C.
6. Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.

#### **AC Loading and Waveforms**



#### NOTES:

- 1. Input driven by 50  $\Omega$  source terminated in 50  $\Omega$ .
- 2. CL includes load and stray capacitance.
- ${}^{*}C_{L} = 50 pF$

Figure 3. AC Test Circuit

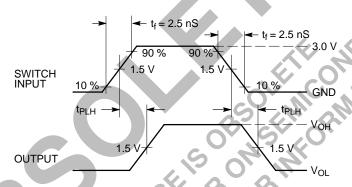


Figure 4. Propagation Delays

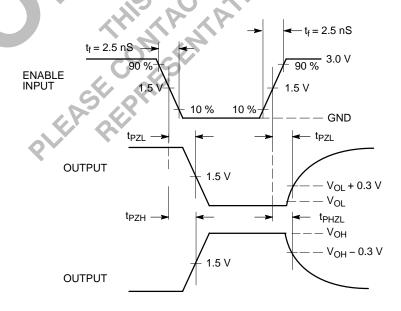
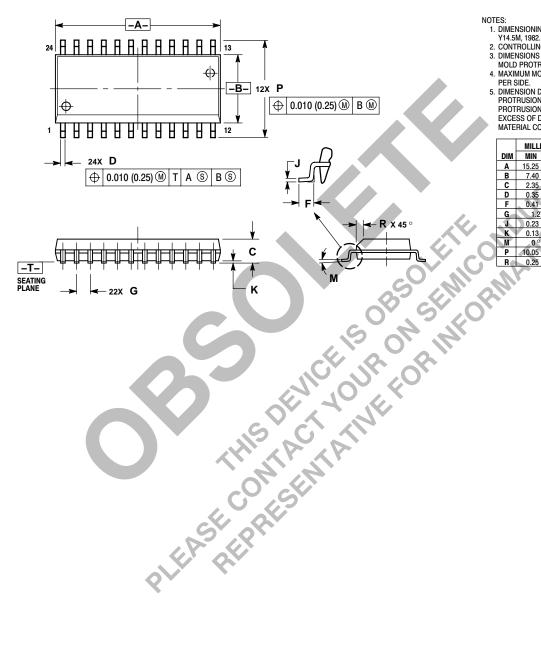


Figure 5. Enable/Disable Delays

#### PACKAGE DIMENSIONS

SOIC-24 **D SUFFIX** CASE 751E-04 ISSUE E



#### NOTES:

- OTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)

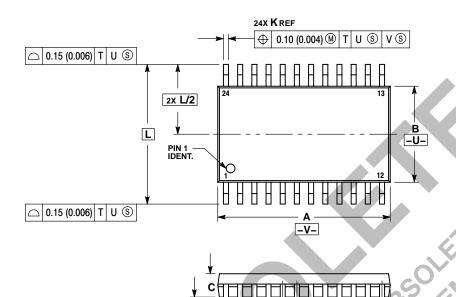
- PER SIDE.

  5. DIMENSION D DOES NOT INCLUDE DAMBAR DIMENSION D DUES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN
  EXCESS OF D DIMENSION AT MAXIMUM
  MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX <	MIN	MAX
Α	15.25	15.54	0.601	0.612
В	7.40	7.60	0.292	0.299
С	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27	BSC	0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0 °	8°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

#### PACKAGE DIMENSIONS

#### TSSOP-24 **DT SUFFIX** CASE 948H-01 **ISSUE A**





- NOTES:

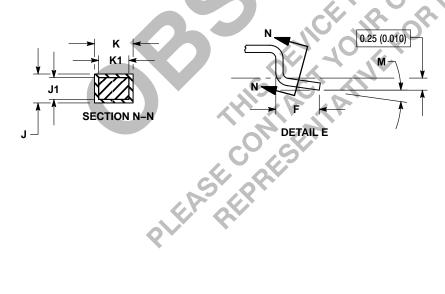
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 114.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) DED SIDE.
- OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006)
  PER SIDE.
  DIMENSION B DOES NOT INCLUDE INTERLEAD
  FLASH OR PROTRUSION. INTERLEAD FLASH OR
  PROTRUSION SHALL NOT EXCEED
  0.25 (0.010) PER SIDE.
  DIMENSION K DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION. SHALL DEED DAMBAR
  PROTRUSION. SHALL DEED DAMBAR
- PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

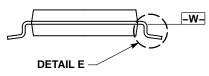
  6. TERMINAL NUMBERS ARE SHOWN FOR
- PEFERENCE ONLY.
  DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	7.70	7.90	0.303	0.311
В	4.30	4.50	0.169	0.177
C		1.20		0.047
D	0.05	0.15	0.002	0.006
F ⊿	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	
M	0°	8°	0°	8°



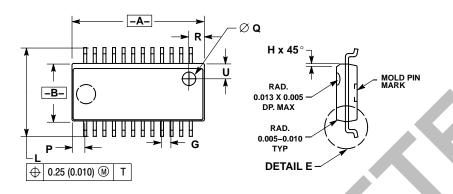
☐ 0.10 (0.004) -T- SEATING

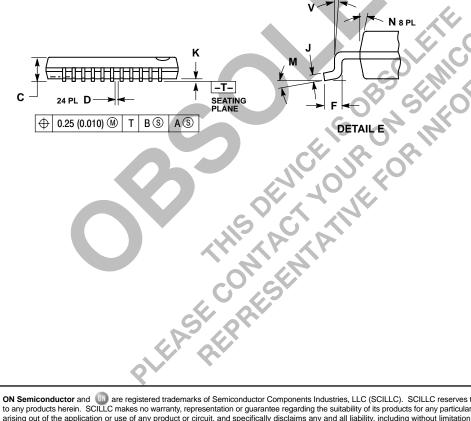
D



#### PACKAGE DIMENSIONS

#### QSOP-24 QS SUFFIX CASE 492B-01 ISSUE O





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: INCH
- 3. THE BOTTOM PACKAGE SHALL BE BIGGER THAN THE TOP PACKAGE BY 4 MILS (NOTE: LEAD SIDE ONLY). BOTTOM PACKAGE DIMENSION SHALL FOLLOW THE DIMENSION STATED IN THIS DRAWING.
- PLASTIC DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 6 MILS PER SIDE.
- 5. BOTTOM EJECTOR PIN WILL INCLUDE THE COUNTRY OF ORIGIN (COO) AND MOLD CAVITY I.D.

	INC	HES	MILLIM	ETERS
DIM	MAX	MIN	MAX	MIN
Α	0.337	0.344	8.56	8.74
В	0.150	0.157	3.81	3.99
С	0.061	0.068	1.55	1.73
D	0.008	0.012	0.20	0.31
F	0.016	0.035	0.41	0.89
G	0.025	BSC 🔦	0.64	BSC
H	0.008	0.018	0.20	0.46
Ĺ	0.0098	0.0075	0.249	0.191
K	0.004	0.010	0.10	0.25
) Ľ	0.230	0.244	5.84	6.20
M	0 0	8°	0°	8°
N	0°	7°	0°	7°
P	0.027	0.037	0.69	0.94
Q	0.035	DIA	0.89	DIA
R	0.035	0.045	0.89	1.14
U	0.035	0.045	0.89	1.14
٧	0 °	8°	0°	8°

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